



Material Content Data Sheet



Sales Product Name		TLE4254EJ S		Issued		28. August 2013		
MA#		MA001140058						
Package		PG-DSO-8-27		Weight*		84.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.802	2.14	2.14	21403	21403
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.728	0.86		8643	
wire	non noble metal	copper	7440-50-8	29.548	35.10	36.01	350954	360137
	noble metal	gold	7440-57-5	0.113	0.13	0.13	1337	1337
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1172
plastics	plastics	epoxy resin	-	4.540	5.39		53922	
	inorganic material	silicondioxide	60676-86-0	44.707	53.11	58.62	531009	586103
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8256	8256
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8605	8605
glue	plastics	epoxy resin	-	0.298	0.35		3540	
	noble metal	silver	7440-22-4	0.894	1.06	1.41	10619	14159
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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